

IN THE CLAIMS:

2010  
1. (Currently Amended) A ~~component-placement~~ machine for placing components on a printed circuit board, comprising:

- a transport device for transporting printed circuit boards in an X-direction;
- at least one feeder area with components;
- a Y-slide, which is independently drivable in the X-direction; and
- at least two placement heads on said Y-slide, each of the at least two placement heads being capable of placing components from the at least one feeder area onto the printed circuit board,

wherein each of the at least two placement heads move simultaneously in the X-direction and are independently drivable in a Y-direction.

2. (Currently Amended) The ~~component-placement~~ machine as claimed in claim 1, further comprising a plurality of Y-slides, each of which are independently drivable in the X-direction, each of the plurality of Y-slides being provided with at least two placement heads.

3. (Previously Amended) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- in a first period of time, moving a first placement head to a desired X-Y position above a first feeder and, subsequently, picking up a component from the first feeder,

moving a second placement head along a Y-slide to a desired Y-position so as to prepare for the placement of a previously picked-up component on the printed circuit board,

- in a second period of time following the first period of time, moving the second placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board,

- in a third period of time following the second period of time, moving the second placement head to a desired X-Y position above a second feeder and, subsequently, picking up a component from the second feeder, moving the first placement head along the Y-slide to a desired Y-position so as to prepare for the placement on the printed circuit board of the component picked up in the first period of time, and

- in a fourth period of time following the third period of time, moving the first placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board.

4. (Previously Amended) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- in a first period of time, moving a first series of placement heads to a desired X-Y position above a first feeder and, subsequently, simultaneously picking up components from the first feeder, moving a second series of placement heads along one of a multitude of Y-slides to a desired Y-position so as to prepare for the placement on the printed circuit board of previously picked-up components,

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- in a second period of time following the first period of time, moving the second series of placement heads to a desired X-Y position above the printed circuit board and, subsequently, placing the components simultaneously on the printed circuit board,

- in a third period of time following the second period of time, moving the second series of placement heads to a desired X-Y position above a second feeder and, subsequently, simultaneously picking up components from the second feeder, moving the first series of placement heads moves along the one of a multitude of Y-slides to a desired Y-position so as to prepare for the placement on the printed circuit board of the components picked up in the first period of time, and

in a fourth period of time following the third period of time, moving the first series of placement heads to a desired X-Y position above the printed circuit board and, subsequently, placing the components simultaneously on the printed circuit board.

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*Concluded*